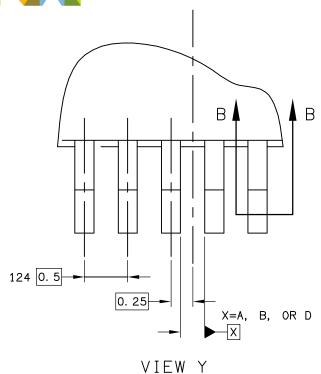
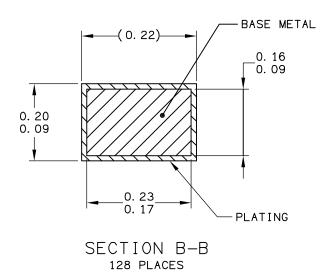
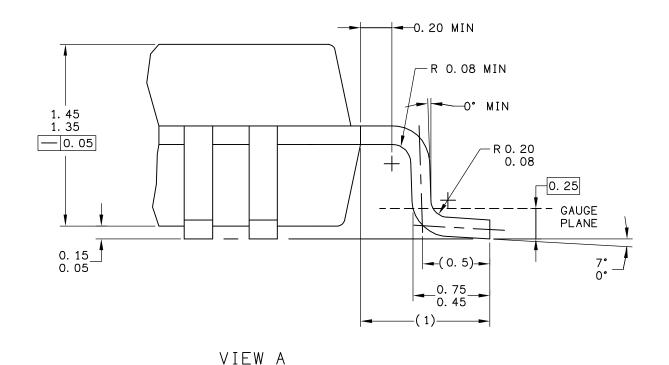


NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OU	TLINE	PRINT VERSION N	OT TO SCALE
TITLE: 128 LEAD LQFP	4 THICK	DOCUMEN	NT NO: 98ASS23663W	REV: C
14 X 20 MM, 0.5 PITCH, 1.		STANDARD: JEDEC MS-026 BHB		
		S0T425-	-2	27 JAN 2016









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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

DOCUMENT NO: 98ASS23663W REV: C

STANDARD: JEDEC MS-026 BHB

SOT425-2 27 JAN 2016



## NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- A DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
- THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 mm AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 mm.
- A: THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
- A EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- AND 0.25 mm FROM THE LEAD TIP.

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